

## AMENDMENTS TO THE CLAIMS

### **Claims 1-39 (Cancelled)**

**Claim 40 (Currently Amended)** An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

a polishing table having a polishing surface;

a substrate carrier having a lower surface for holding the substrate and bringing the substrate into contact with said polishing surface, said substrate carrier having a polishing position in which both the first layer and the second layer of the substrate are polished and in which said substrate carrier is positioned such that a portion of the lower surface of said substrate carrier extends radially outwardly of the outer peripheral portion of said polishing table such that the substrate extends outwardly of the outer peripheral portion of said polishing table;

an attitude control mechanism structured and arranged to keep said lower surface of said substrate carrier parallel with said polishing surface in said polishing position;

a liquid supply nozzle for supplying a first polishing liquid during a polishing process while polishing a the first layer, and for supplying a second polishing liquid while polishing a the second layer;

a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer; and

a thickness measurement device positioned at an outer peripheral portion of said polishing table so as to be positioned below said substrate carrier, and thus the substrate carried by said substrate carrier, in said polishing position during polishing of the first layer and the second layer of the substrate when holding the substrate in said polishing position.

**Claim 41 (Previously Presented)** An apparatus claimed in claim 40, further comprising a second nozzle for providing water toward the surface of the substrate for cleaning the surface of the substrate after being polished.

**Claims 42-43 (Canceled)**

**Claim 44 (Currently Amended)** An apparatus for polishing a substrate having a surface on which a first layer and a second layer are formed, comprising:

a polishing table having a polishing surface the diameter of which is substantially 1.5 times the diameter of the substrate;

a substrate carrier having a lower surface for holding a the substrate and bringing the substrate into contact with a said polishing surface;

a polishing table having said polishing surface, the diameter of which is substantially 1.5 times the diameter of the lower surface of said substrate carrier;

a pivotal shaft for rotatably supporting the said substrate carrier for movement to and from a polishing position, ~~in which polishing position both the first layer and the second layer of the substrate are polished, and in which polishing position said substrate carrier is positioned such that a portion of the lower surface of the substrate carrier extends radially outwardly of the an outer peripheral portion of said polishing table such that the substrate extends outwardly of the outer peripheral portion of said polishing table;~~

an attitude control mechanism for keeping said lower surface of said substrate carrier parallel with said polishing surface;

a liquid supply nozzle for supplying a first polishing liquid during a while polishing process of a the first layer, and for supplying a second polishing liquid while polishing a the second layer;

a first nozzle for providing water toward said polishing surface for cleaning said polishing surface after polishing the first layer and before polishing the second layer;

a thickness measurement device for determining an end point of said polishing of said first layer process, said thickness measurement device being positioned at the outer peripheral portion of said polishing table so as to be positioned below said substrate carrier, ~~and thus the substrate carried by said substrate carrier, in said polishing position during polishing of the first layer and the second layer of the substrate holding the substrate in said polishing position; and~~

a second nozzle for providing water toward the surface of the substrate for cleaning the surface after being polished.

**Claim 45 (Previously Presented)** An apparatus claimed in claim 44, wherein said attitude control mechanism comprises at least an electromagnetic coil and a drive circuit for energizing the electromagnetic coil.

**Claim 46 (Previously Presented)** An apparatus claimed in claim 45, wherein the temperature of said polishing liquid is controlled so as to keep constant level.

**Claim 47 (Canceled)**

**Claim 48 (Currently Amended)** An apparatus claimed in claim 40, wherein the diameter of said polishing table is substantially-1.5 times the diameter of the lower surface of the substrate carrier.